

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 – 12 (Canceled).

Claim 13 (Currently amended): Semiconductor device manufacturing equipment comprising:

~~As a transfer chamber having a first side and a second side located directly across the interior of the transfer chamber from said first side, said first and second sides of said transfer chamber extending in vertical planes, respectively, that are parallel to one another;~~

a plurality of load lock chambers connected to said transfer chamber independently of each other at said first side of the transfer chamber, some of said loadlock chambers being disposed at a plurality of levels, respectively, at said first side of said transfer chamber, a number of said ~~load lock~~ load lock chambers being disposed side-by-side ~~as oriented parallel to one another and spaced relative to each other in a first axial direction on at least one of said levels, the first axial direction lying parallel to the planes in which said first and second sides of the transfer chamber lie,~~ and each of said load lock chambers having first and second doors that separate

the interior of the load lock chamber from the environment outside the equipment and the interior of said transfer chamber, respectively;

a plurality of process chambers in which wafers are processed, said process chambers being connected to said transfer chamber independently of each other at said second side of said transfer chamber, each of said process chambers being disposed directly across said transfer chamber from a respective one of said ~~load lock~~ load lock chambers and vice versa, whereby wherein some of said process chambers are disposed at said plurality of levels, respectively, at said second side of the transfer chamber, and a number of said ~~load lock~~ process chambers are disposed side-by-side as oriented parallel to one another and spaced relative to each other in said first axial direction on said at least one of said levels; and

a robot disposed in said transfer chamber, said robot comprising a robot arm, and a wafer support member disposed at a terminal end of said robot arm so as to move with said robot arm, said robot arm being supported so as to be independently linearly translatable in said first axial direction, linearly translatable in a vertical direction, and rotatable about a vertical axis, and said wafer support member being supported by said robot arm so as to be extendable and retractable independently of said robot arm at said terminal end of the robot arm, wherein the robot has a working envelope that allows the wafer support member to transfer wafers between any of said load lock chambers and the respective process chamber disposed across therefrom.

Claim 14 (New): Semiconductor device manufacturing equipment as claimed in claim 13, wherein said transfer chamber has the shape of a rectangular parallelepiped.